

ON Semiconductor

ISL9V5036S3S / ISL9V5036P3 / ISL9V5036S3

EcoSPARK® 500mJ, 360V, N-Channel Ignition IGBT

General Description

The ISL9V5036S3S, ISL9V5036P3, and ISL9V5036S3 are the next generation IGBTs that offer outstanding SCIS capability in the D²-Pak (TO-263) and TO-220 plastic package. These devices are intended for use in automotive ignition circuits, specifically as coil drivers. Internal diodes provide voltage clamping without the need for external components.

EcoSPARK® devices can be custom made to specific clamp voltages. Contact your nearest ON Semiconductor sales office for more information.

Formerly Developmental Type 49443

Applications

- · Automotive Ignition Coil Driver Circuits
- · Coil-On Plug Applications

Features

- Industry Standard D2-Pak package
- SCIS Energy = 500mJ at T_J = 25°C
- · Logic Level Gate Drive
- · Qualified to AEC Q101
- · RoHS Compliant



Package Symbol JEDEC TO-263AB JEDEC TO-220AB JEDEC TO-262AA D²-Pak G COLLECTOR (FLANGE) Symbol GATE COLLECTOR (FLANGE)

Device Maximum Ratings $T_A = 25$ °C unless otherwise noted

Symbol	Parameter	Ratings	Units V	
BV _{CER}	Collector to Emitter Breakdown Voltage (I _C = 1 mA)	390		
BV _{ECS}	Emitter to Collector Voltage - Reverse Battery Condition (I _C = 10 mA)	24	V	
E _{SCIS25}	At Starting $T_J = 25$ °C, $I_{SCIS} = 38.5$ A, $L = 670 \mu Hy$	500	mJ	
E _{SCIS150}	At Starting $T_J = 150$ °C, $I_{SCIS} = 30$ A, $L = 670 \mu Hy$	300	mJ	
I _{C25}	Collector Current Continuous, At T _C = 25°C, See Fig 9	46	Α	
I _{C110}	Collector Current Continuous, At T _C = 110°C, See Fig 9	31	Α	
V _{GEM}	Gate to Emitter Voltage Continuous	±10	V	
P _D	Power Dissipation Total T _C = 25°C	250	W	
	Power Dissipation Derating T _C > 25°C	1.67	W/°C	
TJ	Operating Junction Temperature Range	-40 to 175	°C	
T _{STG}	Storage Junction Temperature Range	-40 to 175	°C	
TL	Max Lead Temp for Soldering (Leads at 1.6mm from Case for 10s)	300	°C	
T _{pkg}	Max Lead Temp for Soldering (Package Body for 10s)	260	°C	
ESD	Electrostatic Discharge Voltage at 100pF, 1500Ω	4	kV	

Device I	Narking	Device	Package	Reel Size	•	Tape Wid	lth	Quantity
V5036S		ISL9V5036S3ST	TO-263AB	330mm		24mm		800
V5036P		ISL9V5036P3	TO-220AA	Tube		N/A		50
V5036S		ISL9V5036S3	TO-262AA	Tube	N/A			50
V5036S		ISL9V5036S3S	TO-263AB	Tube		N/A		50
Electric	al Chara	acteristics T _A = 25°C	unless otherwise	noted				
Symbol		Parameter		Test Conditions		Тур	Max	Units
Off State	Characte	ristics						
BV _{CER}	Collector to Emitter Breakdown Voltage		$R_G = 1K\Omega$, So	$I_C = 2\text{mA}, V_{GE} = 0,$ $R_G = 1\text{K}\Omega, \text{ See Fig. 15}$ $T_J = -40 \text{ to } 150^{\circ}\text{C}$		360	390	V
BV _{CES}	Collector to Emitter Breakdown Voltage		$\begin{array}{c} I_C = 10\text{mA}, V_C \\ R_G = 0, \text{ See} \end{array}$	$I_C = 10$ mA, $V_{GE} = 0$, $R_G = 0$, See Fig. 15 $T_J = -40$ to 150°C		390	420	V
BV _{ECS}	Emitter to Collector Breakdown Voltage			$I_C = -75 \text{mA}, V_{GE} = 0 \text{V},$		-	-	V
BV _{GES}	Gate to Er	Gate to Emitter Breakdown Voltage		I _{GES} = ± 2mA		±14	-	V
I _{CER}	Collector t	o Emitter Leakage Current	$V_{CER} = 250V,$		-	-	25	μΑ
-			$R_G = 1K\Omega$, See Fig. 11	T _C = 150°C	-	-	1	mA
I _{ECS}	Emitter to	Collector Leakage Current	$V_{EC} = 24V$, Se		-	-	1	mA
			Fig. 11	$T_C = 150$ °C	-	-	40	mA
R ₁	Series Ga	te Resistance			-	75	-	Ω
R ₂ On State	Characte	nitter Resistance			10K	-	30K	Ω
V _{CE(SAT)}		o Emitter Saturation Voltage	e I _C = 10A,	T _C = 25°C,	-	1.17	1.60	V
02(0/)			$V_{GE} = 4.0V$	See Fig. 4				
V _{CE(SAT)}	Collector t	o Emitter Saturation Voltage	$I_C = 15A,$ $V_{GE} = 4.5V$	T _C = 150°C	-	1.50	1.80	V
Dynamic	Characte	ristics						
$Q_{G(ON)}$	Gate Cha	rge		I _C = 10A, V _{CE} = 12V, V _{GE} = 5V, See Fig. 14		32	-	nC
V _{GE(TH)}	Gate to Er	mitter Threshold Voltage	$I_C = 1.0 \text{mA},$	T _C = 25°C	1.3	-	2.2	V
,			$V_{CE} = V_{GE}$, See Fig. 10	T _C = 150°C	0.75	-	1.8	V
V_{GEP}	Gate to Er	mitter Plateau Voltage	$I_{C} = 10A,$	$V_{CE} = 12V$	-	3.0	-	V
Switching	Charact	eristics						
t _{d(ON)R}	Current Turn-On Delay Time-Resistive		$V_{CF} = 14V, R_{I}$	$V_{CE} = 14V, R_{L} = 1\Omega,$		0.7	4	μs
t _{rR}	Current R	ise Time-Resistive	$V_{GE} = 5V$, $R_G = 1K\Omega$ $T_J = 25$ °C, See Fig. 12		-	2.1	7	μs
t _{d(OFF)L}	Current Tu	ırn-Off Delay Time-Inductive		V _{CE} = 300V, L = 2mH,		10.8	15	μs
t _{fL}		all Time-Inductive	$T_J = 25$ °C, Se	$V_{GE} = 5V$, $R_G = 1K\Omega$ $T_J = 25$ °C, See Fig. 12			15	μs
SCIS	Self Clamped Inductive Switching				-	-	500	mJ

TO-263, TO-220, TO-262

0.6

°C/W

 $R_{\theta JC}$

Thermal Resistance Junction-Case

Typical Characteristics

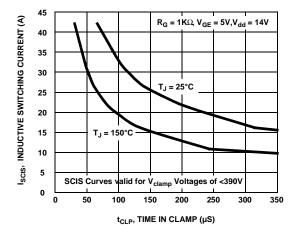


Figure 1. Self Clamped Inductive Switching Current vs Time in Clamp

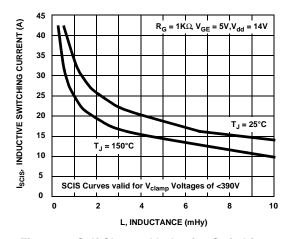


Figure 2. Self Clamped Inductive Switching Current vs Inductance

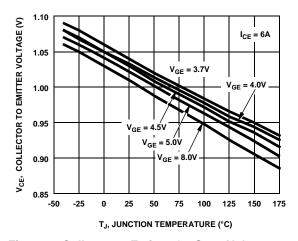


Figure 3. Collector to Emitter On-State Voltage vs Junction Temperature

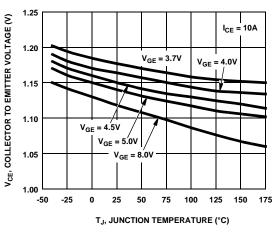


Figure 4.Collector to Emitter On-State Voltage vs Junction Temperature

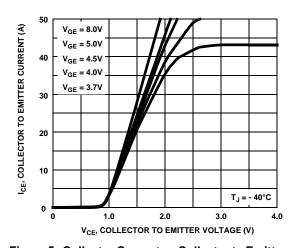


Figure 5. Collector Current vs Collector to Emitter On-State Voltage

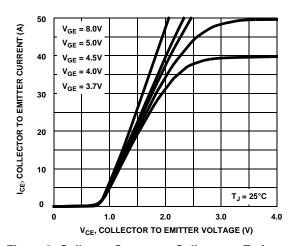


Figure 6. Collector Current vs Collector to Emitter On-State Voltage

(F) V_{GE} = 8.0V V_{GE} = 5.0V V_{GE} = 4.5V V_{GE} = 4.5V V_{GE} = 3.7V V

Typical Characteristics (Continued)

Figure 7. Collector to Emitter On-State Voltage vs Collector Current

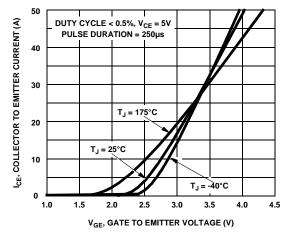


Figure 8. Transfer Characteristics

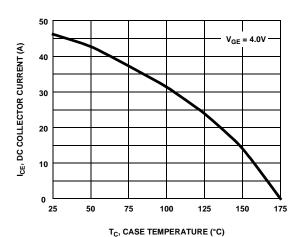


Figure 9. DC Collector Current vs Case Temperature

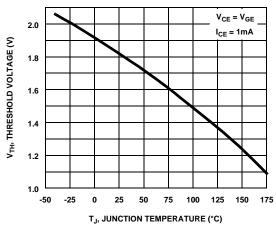


Figure 10. Threshold Voltage vs Junction Temperature

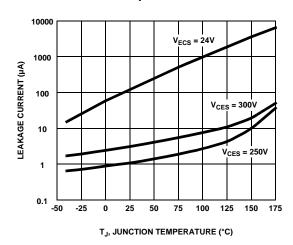


Figure 11. Leakage Current vs Junction Temperature

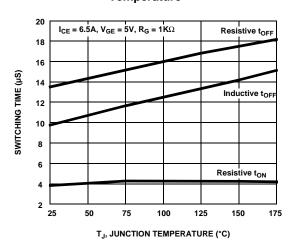


Figure 12. Switching Time vs Junction Temperature

3000 FREQUENCY = 1 MHz 2500 C, CAPACITANCE (pF) 2000 CIES 1500

 $\mathbf{C}_{\mathsf{RES}}$

1000

500

0

Typical Characteristics (Continued)

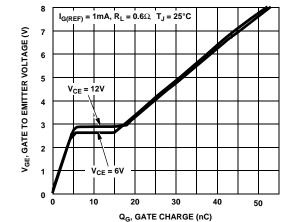


Figure 13. Capacitance vs Collector to Emitter Voltage

V_{CE}, COLLECTOR TO EMITTER VOLTAGE (V)

10

 \textbf{C}_{OES}

20

15

Figure 14. Gate Charge

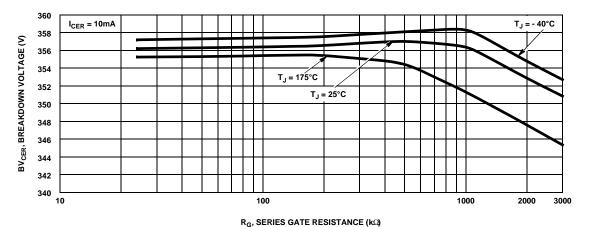


Figure 15. Breakdown Voltage vs Series Gate Resistance

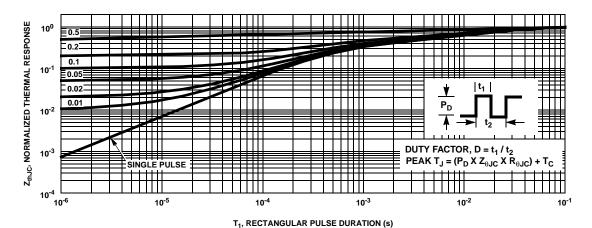


Figure 16. IGBT Normalized Transient Thermal Impedance, Junction to Case

Test Circuits and Waveforms

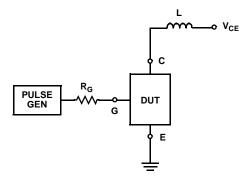


Figure 17. Inductive Switching Test Circuit

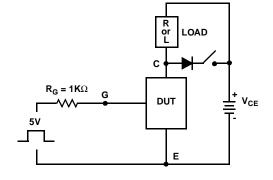


Figure 18. t_{ON} and t_{OFF} Switching Test Circuit

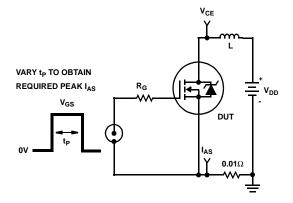


Figure 19. Energy Test Circuit

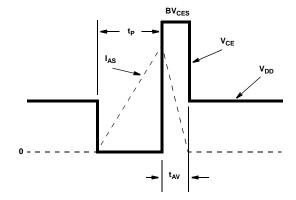
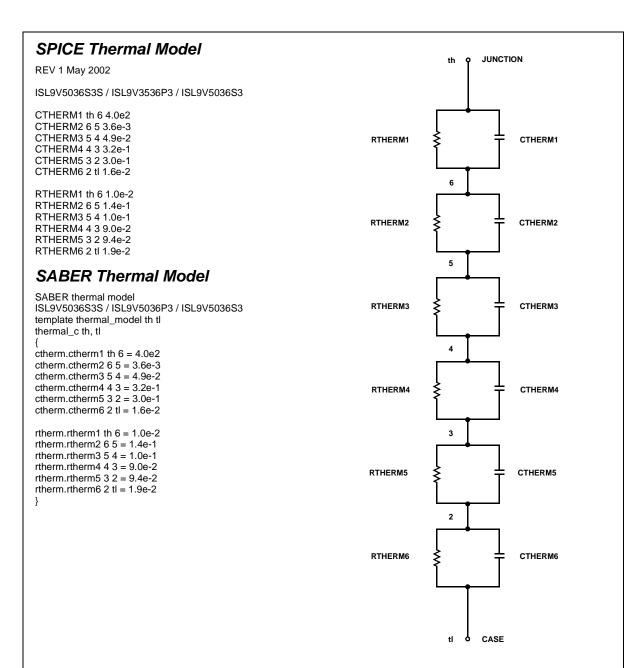


Figure 20. Energy Waveforms



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